

July 2014

MMBT2222A / PZT2222A NPN General-Purpose Amplifier

Features

- This device is for use as a medium power amplifier and switch requiring collector currents up to 500mA.
- · Sourced from process 19.

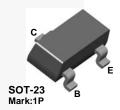


Figure 1. MMBT2222A Device Package

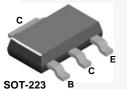


Figure 2. PZT2222A Device Package

Ordering Information

| Part Number | Top Mark | Package | Packing Method |
|-------------|----------|------------|----------------|
| MMBT2222A | 1P | SOT-23 3L | Tape and Reel |
| PZT2222A | 2222A | SOT-223 4L | Tape and Reel |

Absolute Maximum Ratings(1), (2)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at $T_A = 25^{\circ}\text{C}$ unless otherwise noted.

| Symbol | Parameter | Value | Unit |
|------------------|--|------------|------|
| V _{CEO} | Collector-Emitter Voltage | 40 | V |
| V _{CBO} | Collector-Base Voltage | 75 | V |
| V _{EBO} | Emitter-Base Voltage | 6.0 | V |
| I _C | Collector Current | 1.0 | Α |
| T _{STG} | Operating and Storage Junction Temperature Range | -55 to 150 | °C |

Note:

- 1. These rating are based on a maximum junction temperature of 150 °C.
- 2. These are steady-state limits. Fairchild Semiconductor should be consulted on applications involving pulsed or low-duty-cycle operation.

Thermal Characteristics

Values are at $T_A = 25$ °C unless otherwise noted.

| Symbol | Parameter | Ma | Unit | |
|-----------------|---|--------------------------|-------------------------|-------|
| | Faiailletei | MMBT2222A ⁽³⁾ | PZT2222A ⁽⁴⁾ | John |
| P _D | Total Device Dissipation | 350 | 1000 | mW |
| | Derate Above 25°C | 2.8 | 8.0 | mW/°C |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient | 357 | 125 | °C/W |

Notes:

- 3. Device is mounted on FR-4 PCB 1.6 inch x 1.6 inch x 0.06 inch.
- 4. Device is mounted on FR-4 PCB 36 mm x 18 mm x 1.5 mm, mounting pad for the collector lead minimum 6 cm².

Electrical Characteristics

Values are at $T_A = 25$ °C unless otherwise noted.

| Symbol | Parameter | Conditions | Min. | Max. | Unit |
|-----------------------|---|---|------|------|------|
| Off Charact | eristics | | | | • |
| BV _{(BR)CEO} | Collector-Emitter Breakdown Voltage ⁽⁵⁾ | I _C = 10 mA, I _B = 0 | 40 | | V |
| BV _{(BR)CBO} | Collector-Base Breakdown Voltage | $I_C = 10 \mu\text{A}, I_E = 0$ | 75 | | V |
| BV _{(BR)EBO} | Emitter-Base Breakdown Voltage | $I_E = 10 \mu\text{A}, I_C = 0$ | 6.0 | | V |
| I _{CEX} | Collector Cut-Off Current | $V_{CE} = 60 \text{ V}, V_{EB(off)} = 3.0 \text{ V}$ | | 10 | nA |
| I _{CBO} | Collector Cut-Off Current | $V_{CB} = 60 \text{ V}, I_{E} = 0$ | | 0.01 | μΑ |
| | | $V_{CB} = 60 \text{ V}, I_{E} = 0, T_{A} = 125^{\circ}\text{C}$ | | 10 | |
| I _{EBO} | Emitter Cut-Off Current | $V_{EB} = 3.0 \text{ V}, I_{C} = 0$ | | 10 | nA |
| I _{BL} | Base Cut-Off Current | V _{CE} = 60 V, V _{EB(off)} = 3.0 V | | 20 | nA |
| On Characte | eristics | | | | • |
| | | $I_C = 0.1 \text{ mA}, V_{CE} = 10 \text{ V}$ | 35 | | |
| | | I _C = 1.0 mA, V _{CE} = 10 V | 50 | | 1 |
| | | I _C = 10 mA, V _{CE} = 10 V | 75 | | |
| h _{FE} | DC Current Gain | I _C = 10 mA, V _{CE} = 10 V, T _A = -55°C | 35 | | |
| | | $I_C = 150 \text{ mA}, V_{CE} = 10 \text{ V}^{(5)}$ | 100 | 300 | |
| | | $I_C = 150 \text{ mA}, V_{CE} = 1 \text{ V}^{(5)}$ | 50 | | |
| | | $I_C = 500 \text{ mA}, V_{CE} = 10 \text{ V}^{(5)}$ | 40 | | |
| | Collector-Emitter Saturation Voltage ⁽⁵⁾ | $I_C = 150 \text{ mA}, I_B = 15 \text{ mA}$ | | 0.3 | V |
| V _{CE(sat)} | | $I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$ | | 1.0 | V |
| ., | Base-Emitter Saturation Voltage ⁽⁵⁾ | I _C = 150 mA, I _B = 15 mA | 0.6 | 1.2 | V |
| V _{BE(sat)} | | $I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$ | | 2.0 | |
| Small Signa | I Characteristics | | | | |
| f _T | Current Gain Bandwidth Product | I _C = 20 mA, V _{CE} = 20 V, f = 100 MHz | 300 | | MHz |
| C _{obo} | Output Capacitance | $V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$ | | 8.0 | pF |
| C _{ibo} | Input Capacitance | $V_{EB} = 0.5 \text{ V}, I_{C} = 0, f = 1 \text{ MHz}$ | | 25 | pF |
| rb'C _c | Collector Base Time Constant | I _C = 20 mA, V _{CB} = 20 V, f = 31.8 MHz | | 150 | pS |
| NF | Noise Figure | I_C = 100 μA, V_{CE} = 10 V, R_S = 1.0 kΩ, f = 1.0 kHz | | 4.0 | dB |
| Re(h _{ie}) | Real Part of Common-Emitter High Frequency Input Impedance | I _C = 20 mA, V _{CE} = 20 V, f = 300 MHz | | 60 | Ω |
| Switching C | haracteristics | | | | |
| t _d | Delay Time | $V_{CC} = 30 \text{ V}, V_{EB(off)} = 0.5 \text{ V},$ | | 10 | ns |
| t _r | Rise Time | I _C = 150 mA, I _{B1} = 15 mA | | 25 | ns |
| t _s | Storage Time | $V_{CC} = 30 \text{ V}, I_{C} = 150 \text{ mA},$ | | 225 | ns |
| t _f | Fall Time | I _{B1} = I _{B2} = 15 mA | | 60 | ns |

Note:

5. Pulse test: pulse width $\leq 300~\mu s,$ duty cycle $\leq 2.0\%.$

Typical Performance Characteristics

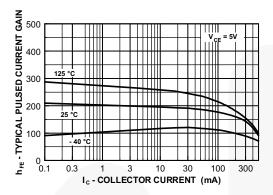


Figure 3. Typical Pulsed Current Gain vs. Collector Current

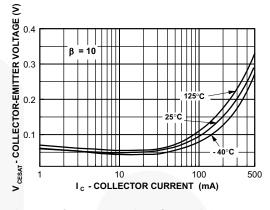


Figure 4. Collector-Emitter Saturation Voltage vs. Collector Current

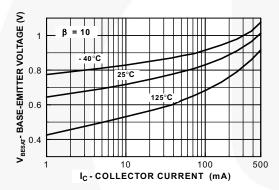


Figure 5. Base-Emitter Saturation Voltage vs. Collector Current

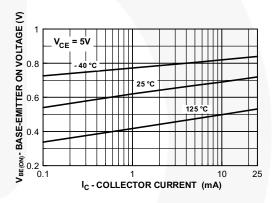


Figure 6. Base-Emitter On Voltage vs. Collector Current

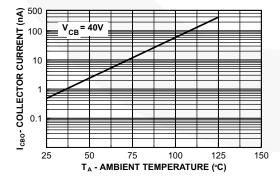


Figure 7. Collector Cut-Off Current vs. Ambient Temperature

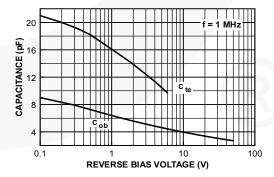


Figure 8. Emitter Transition and Output Capacitance vs. Reverse Bias Voltage

Typical Performance Characteristics (Continued)

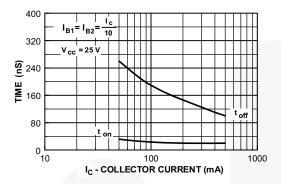


Figure 9. Turn-On and Turn-Off Times vs. Collector Current

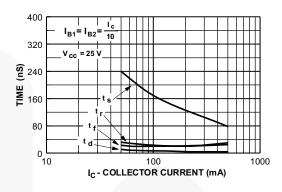


Figure 10. Switching Times vs. Collector Current

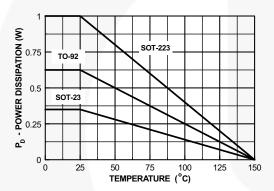


Figure 11. Power Dissipation vs.
Ambient Temperature

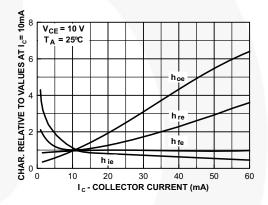


Figure 12. Common Emitter Characteristics

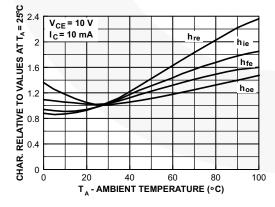


Figure 13. Common Emitter Characteristics

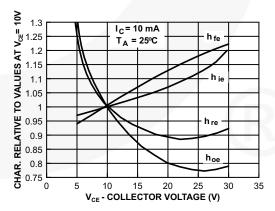


Figure 14. Common Emitter Characteristics

Physical Dimensions

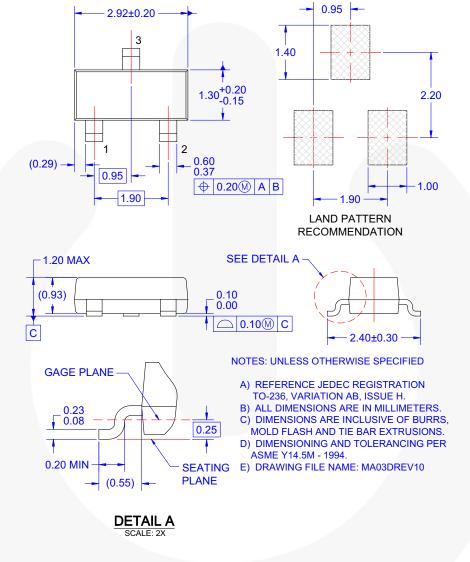


Figure 15. 3-LEAD, SOT23, JEDEC TO-236, LOW PROFILE (ACTIVE)

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Physical Dimensions (Continued)

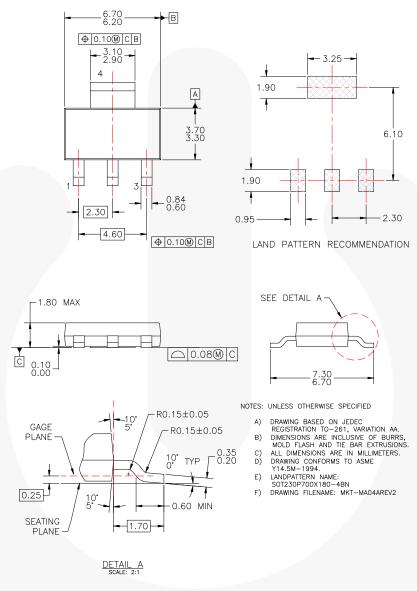


Figure 16. MOLDED PACKAGING, SOT-223, 4-LEAD (ACTIVE)

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